



STEIF POWER
TECHNOLOGY

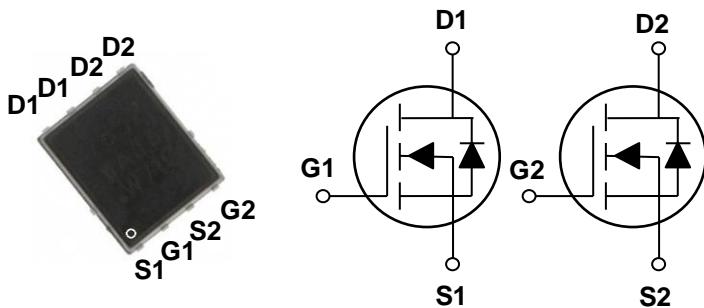
30V N+P Dual Channel MOSFETs

SPC3701T

General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK5x6 Dual Pin Configuration



BVDSS	RDS(on)	ID
30V	12mΩ	23.3A
-30V	29mΩ	-15.2A

Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications
- 100% EAS Guaranteed

Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology



Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating		Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	23.3	-15.2	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	14.7	-9.6	A
I_{DM}	Drain Current – Pulsed ¹	93.2	-60.8	A
EAS	Single Pulse Avalanche Energy ^{2,6}	39.2	39.2	mJ
IAS	Single Pulse Avalanche Current ²	28	28	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	17.4		W
	Power Dissipation – Derate above 25°C	0.14		W/°C
T_{STG}	Storage Temperature Range	-55 to 150		°C
T_J	Operating Junction Temperature Range	-55 to 150		°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62.5	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	7.2	°C/W

**N-CH Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$, $I_D=1\text{mA}$	---	0.04	---	$\text{V}/\text{ }^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^\circ\text{C}$	---	---	1	μA
		$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=10\text{A}$	---	9.4	12	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	---	13	18	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = 250\mu\text{A}$	1.2	1.5	2.5	V
			---	-4	---	$\text{mV}/\text{ }^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=5\text{A}$	---	6.4	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=15\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	---	7.4	12	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	2.3	5	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	3	6	
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=15\text{V}$, $V_{GS}=10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	3.8	7	ns
T_r	Rise Time ^{3, 4}		---	10	19	
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}		---	22	42	
T_f	Fall Time ^{3, 4}		---	6.6	13	
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	620	900	pF
C_{oss}	Output Capacitance		---	85	125	
C_{rss}	Reverse Transfer Capacitance		---	60	90	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	2.8	5.6	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	23.3	A
			---	---	46.6	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^\circ\text{C}$	---	---	1	V

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=28\text{A}$, $R_G=25\Omega$, Starting $T_J=25\text{ }^\circ\text{C}$.
- The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.



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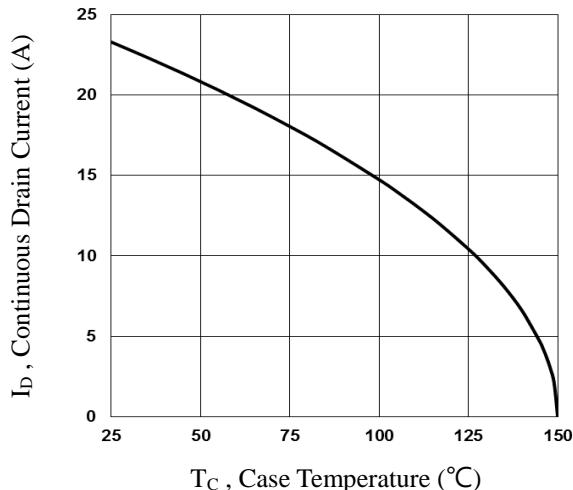


Fig.1 Continuous Drain Current vs. T_c

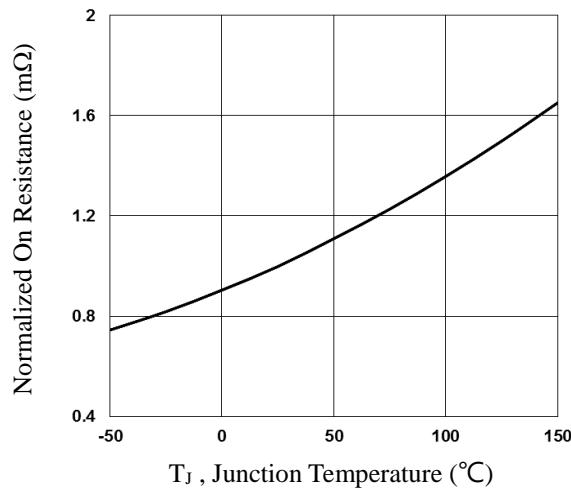


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

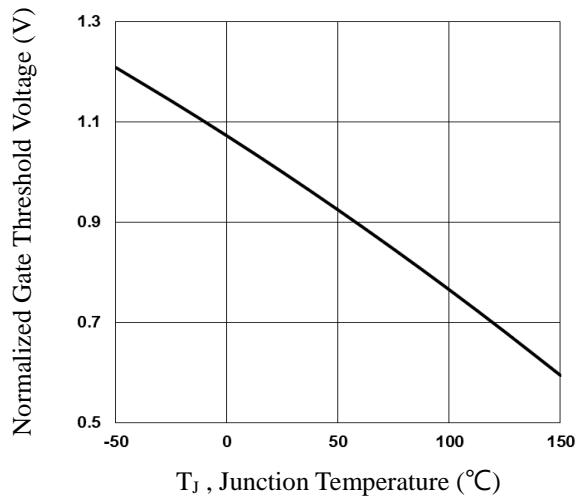


Fig.3 Normalized V_{th} vs. T_J

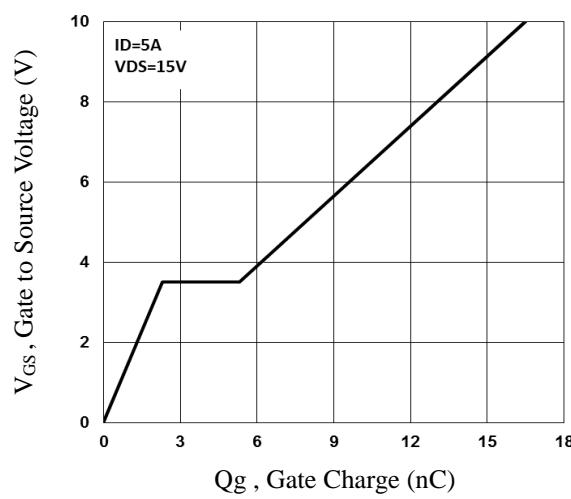


Fig.4 Gate Charge Waveform

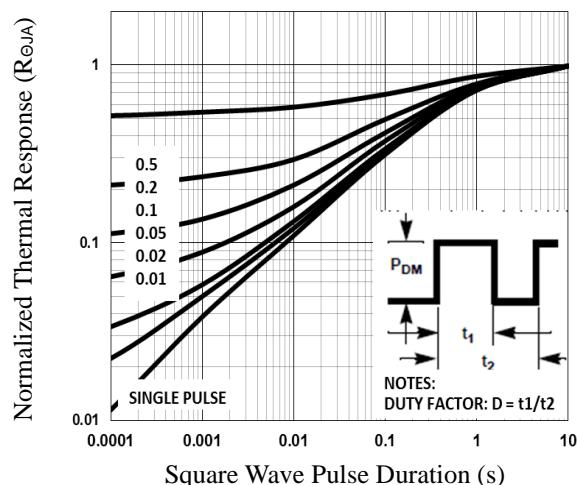


Fig.5 Normalized Transient Response

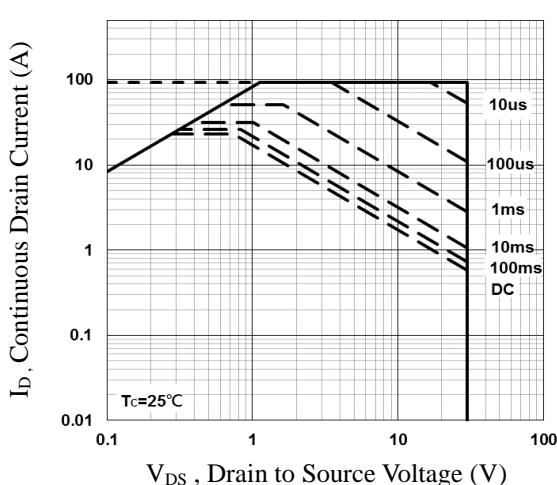


Fig.6 Maximum Safe Operation Area



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P-CH Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$, $I_D=-1\text{mA}$	---	-0.03	---	$\text{V}/\text{ }^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^\circ\text{C}$	---	---	-1	μA
		$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-7\text{A}$	---	24	29	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-4\text{A}$	---	35	46	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
			---	4	---	$\text{mV}/\text{ }^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=-10\text{V}$, $I_D=-3\text{A}$	---	5.4	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{7,8}	$V_{DS}=-15\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-5\text{A}$	---	8	15	nC
Q_{gs}	Gate-Source Charge ^{7,8}		---	3.3	6	
Q_{gd}	Gate-Drain Charge ^{7,8}		---	2.3	5	
$T_{d(on)}$	Turn-On Delay Time ^{7,8}	$V_{DD}=-15\text{V}$, $V_{GS}=-10\text{V}$, $R_G=6\Omega$ $I_D=-1\text{A}$	---	4.6	9	ns
T_r	Rise Time ^{7,8}		---	14	26	
$T_{d(off)}$	Turn-Off Delay Time ^{7,8}		---	34	58	
T_f	Fall Time ^{7,8}		---	18	35	
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	757	1280	pF
C_{oss}	Output Capacitance		---	122	210	
C_{rss}	Reverse Transfer Capacitance		---	88	175	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-15.2	A
I_{SM}	Pulsed Source Current		---	---	-30.4	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25\text{ }^\circ\text{C}$	---	---	-1	V

Note :

5. Repetitive Rating : Pulsed width limited by maximum junction temperature.
6. $V_{DD}=-25\text{V}$, $V_{GS}=-10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=-28\text{A}$, $R_G=25\Omega$, Starting $T_J=25\text{ }^\circ\text{C}$
7. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
8. Essentially independent of operating temperature.



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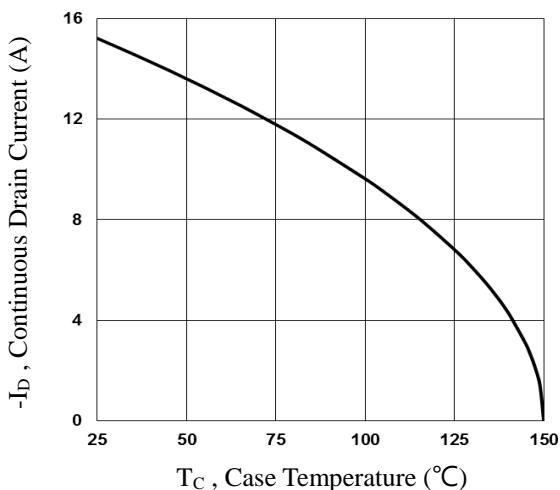


Fig.1 Continuous Drain Current vs. T_c

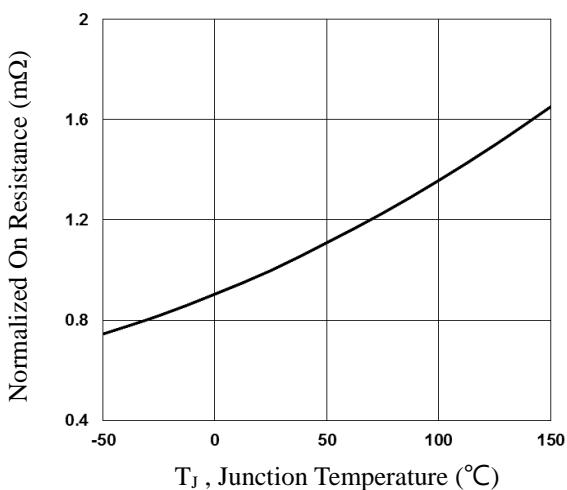


Fig.2 Normalized RD_{SON} vs. T_J

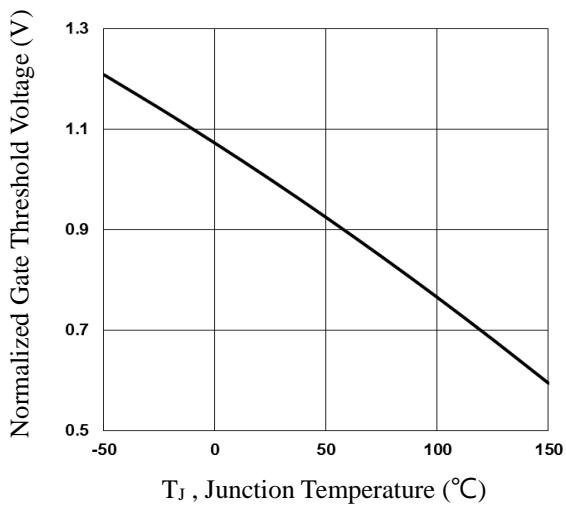


Fig.3 Normalized V_{th} vs. T_J

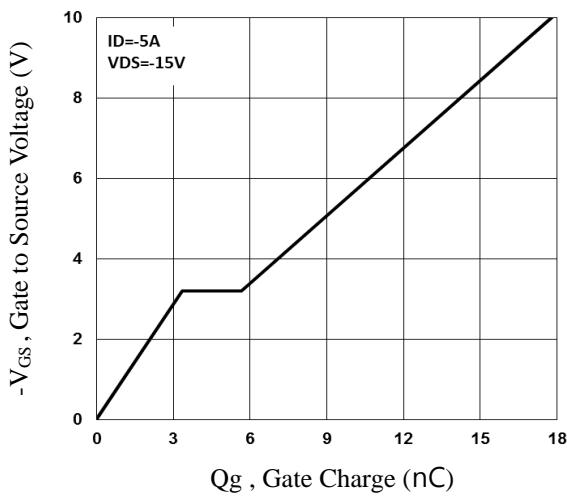


Fig.4 Gate Charge Waveform

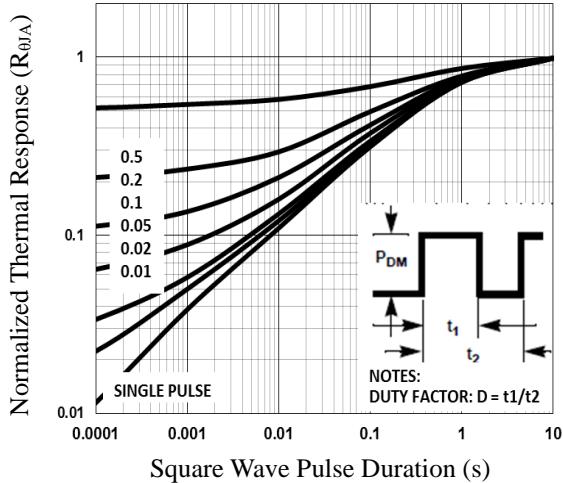


Fig.5 Normalized Transient Impedance

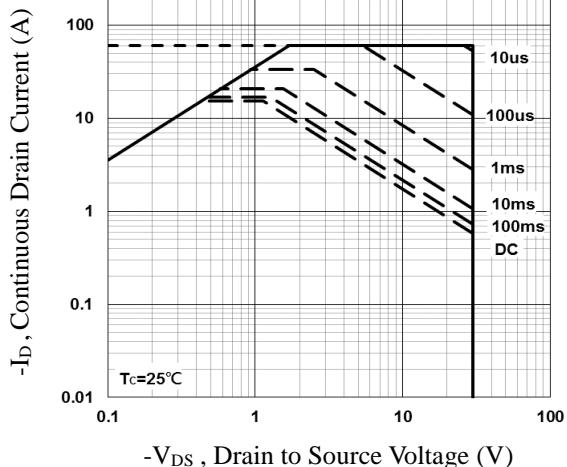
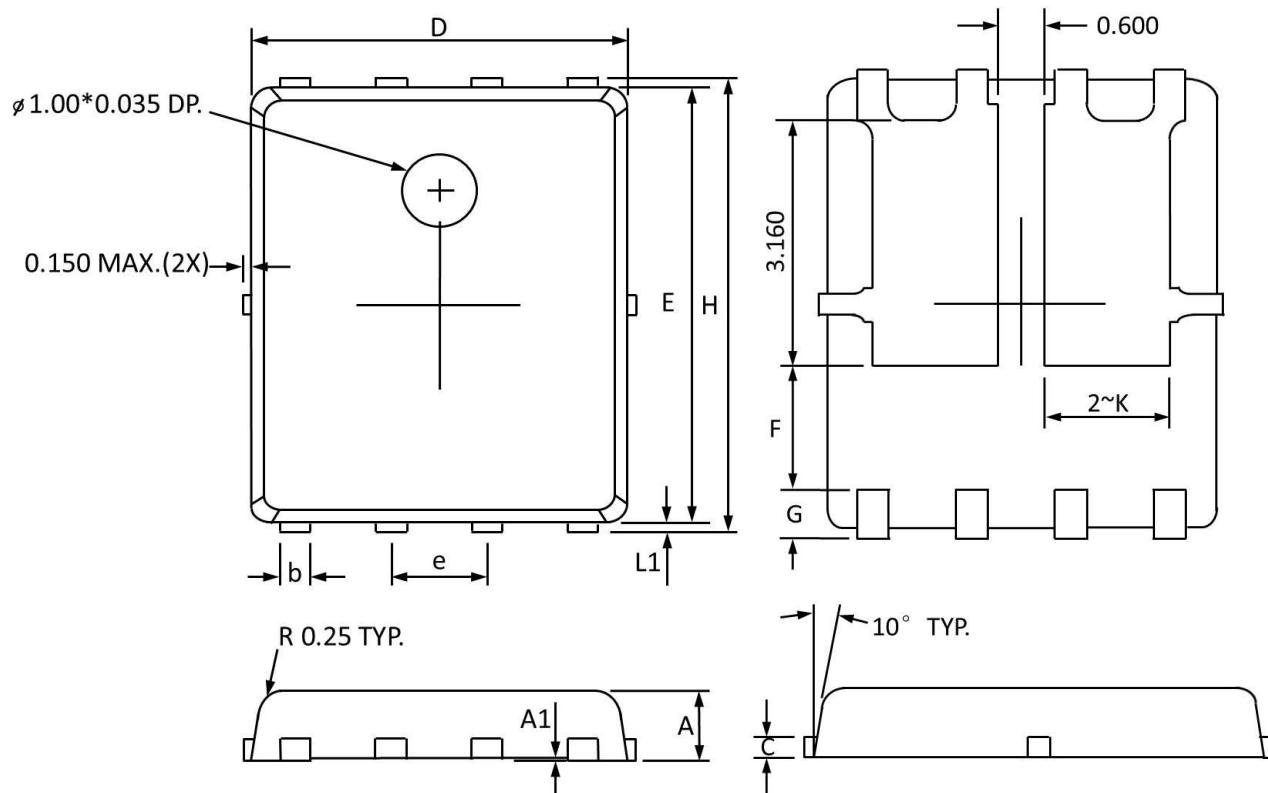


Fig.6 Maximum Safe Operation Area

**PPAK5x6 Dual PACKAGE INFORMATION**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.000	0.032	0.039
A1	0.000	0.005	0.000	0.000
b	0.350	0.490	0.014	0.019
C	0.254 Ref		0.254 Ref	
D	4.900	5.100	0.193	0.200
E	5.700	5.900	0.225	0.232
e	1.27 BSC		1.27 BSC	
F	1.600 Ref		1.600 Ref	
G	0.600 Ref		0.600 Ref	
H	5.950	6.200	0.235	0.244
L1	0.100	0.180	0.004	0.007
K	1.600 Ref		1.600 Ref	